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(71) Applicant: HITACHI CABLE LTD

(72) Inventor: YUMINO SHIGERU

(54) LEAD FRAME FOR MINITRANSISTOR

(57) Abstract:

PURPOSE: To improve waterproofness in a semiconductor chip, by providing a center-lead groove, which is not parallel with a plating border and located between the plating border and an island.

CONSTITUTION: In a lead frame, a semiconductor chip 3 is mounted on an island of a center lead 2. The center lead 2 is connected to collector and emitter leads 1 with each gold conductor 4. The necessary part for chip bonding or wire bonding is plated with silver, and thereby the center lead 2 has a plating border 5 formed therein. A given area of these leads is afterward sealed with resin. In the center lead 2, a center-lead groove 7a, which is not parallel with the plating border 5, is provided between the plating border 5 and the island in the center lead 2. Consequently, the center-lead groove 7a is effectively provided in a narrow space, and the waterproofness in the semiconductor chip can be improved.

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